IPC ASSOCIATION C ELECTRONICS II	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier I	Information													
Company na	ame*	Company unique ID			U	Unique ID Authority				Response Date*				
nsemi											2025-05-12			
Contact Nan	me		Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-En	v-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
uthorized 1	Representative*		Title - Representative			P	Phone - Representative*			Email - Representative*				
Product-En	v-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
F	Requester Item Number	Mfr Item	Number	Mfr Item Name		I	Effective Date	Version	N	Manufacturing Site		eight*	UOM	Unit Type
		NCP810	NCP81080MNTBG Low-Cost High Volt		ltage Dual MOSF	FET 2	2025-05-12		РНМ		9.	1	mg	Each
Ianufact	uring Proccess Inform	ation												
Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			Perminal Base Alloy J-STD-020 MSL Ratio			ating	Peak Process Body Temperature Max Time at Peal				k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy			CU Alloy	1			260		C	30	second	s 3		
omments														
vel 1 - max	ximum time at peak tempera	ture during sol	ldering is 10-3	30 seconds										
or more inf	formation regarding materia	al composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not or written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Die Attach Epoxy	0.07	mg		Epoxy resin	proprietary data		0.007	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0003	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0032	mg
			Supplier	Silver (Ag)	7440-22-4		0.0595	mg
Lead Frame	3.71	mg	Supplier	Silver (Ag)	7440-22-4		0.1484	mg
			Supplier	Tin (Sn)	7440-31-5		0.0093	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0093	mg
			Supplier	Copper (Cu)	7440-50-8		3.5349	mg
Mold Compound-Black	5.0		Supplier	Silica Amorphous (SiO2)	7631-86-9		0.375	mg
			Supplier	Carbon Black (C)	1333-86-4		0.025	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.975	mg
			Supplier	EpoxyNovolaCresins (Cresolic)	64425-89-4		0.25	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.375	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg